

500°F Duralco™ 120

Electrically Conductive Adhesive

- **Resistance is 0.00008 ohm-cm**
- **Just Mix and Apply**
- **Cures at Room Temperature**
- **Ideal For All Applications**

Duralco™ 120 500°F Silver Based

Duralco™ 120 Epoxy Forms Electrically Conductive Bonds for continuous use from -50°F to +500°F.

Contains over 70% Ultra Fine, Active Silver to provide the ultimate in electrical conductivity.

Cures at room temperature. Can be fast cured at moderate temperatures.

Excellent adhesion to copper, steel, stainless, aluminum, lead, glass, ceramics, plastics and dissimilar materials.

Is resistant to moisture, most chemicals and solvents.

Avoids exposing parts to soldering temperatures, flux contamination and provides for process simplification.

Use for electrically conductive bonds, to replace soldering, bonding heat sensitive components, etc.

Resistance of 0.00008 ohm-cm has been reported in independent tests.

Applications include circuits bonding, solder replacement, bonding semi-conductors, EMI shielding, thermistors, wire tacking, heating elements, assembling electronics, etc.

Users Report:

- Duralco™ 120 was used for an application at 200°C for over 12 months with no degradation in electrical conductivity.
- Duralco™ 120 successfully bonded bus bars and carried a current of 2400 amps for a short term test.
- Duralco™ 120 bonds sputtering targets to copper based plates and provides 100°C continuous service.
- New 120SHT bonded Ceramic Transducers for use up to 800°F

Duralco™ 120 is the ideal choice for high power, high temperature, electronic or industrial application requiring high electrical conductivity.

Availability:

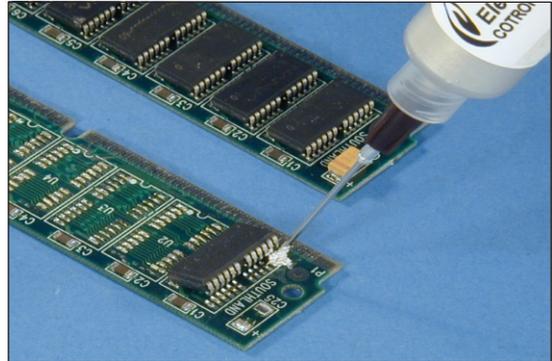
Cat No.	Size	Temp.
Duralco™ 120-1	2 oz. Kit	500°F

Pre-Measured Kits:

EE 120-2	3 EPOX-EEZ™ 10 gm Units/Box
EE 120-3	6 EPOX-EEZ™ 10 gm Units/Box

Each Unit Contains:

1 jar of resin, 1 syringe of hardener and 1 mixing stick.



**Duralco™ 120
In A Surface Mount Application**



**Duralco™ 120
Leads To An Instrument Assembly**

Physical Properties

Max. Use Temperature 500°F

Color	Silver
Base	Ultra Fine Silver
Mixed Viscosity	Smooth Fine Paste
Mixed Density (gm/cc)	3.80
Hardness (Shore D)	70
Lap Shear Strength (psi)	1500
Flexural Strength (psi)	1150
Compressive Strength (psi)	600
Thermal Expansion	4.10 x (10 ⁻⁵ /°C)
Volume Resistivity (ohm-cm)	0.00008
Mix Ratio	100 to 3.4
Thermal Conductivity*	50
Components	2
Cure	R.T. 16 hrs.
	100°F 4 hrs.
	150°F 2 hrs.
	200°F 10 min.
	250°F 7 min.

*(BTU-in/Hr. ft²/F)



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